

WNM20N60S / WNM20N60SF 600V N-Channel MOSFET

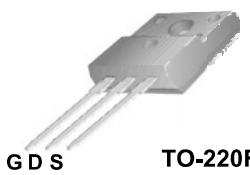
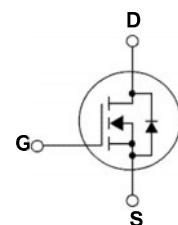
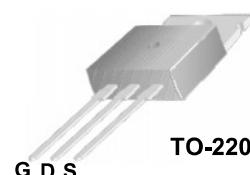
SJ-FET

Description

SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

Features

- 600V @ $T_J = 150^\circ\text{C}$
- Typ. $R_{DS(on)} = 0.155\Omega$
- Ultra Low Gate Charge (typ. $Q_g = 70\text{nC}$)
- 100% avalanche tested



WNM20N60S =Devices code
YY =Year
WW =Week



WNM20N60SF =Devices code
YY =Year
WW =Week

Order information

Device	Package Type	Units/Tube
WNM20N60S-3/T	TO-220	50
WNM20N60SF-3/T	TO-220F	

Absolute Maximum Ratings

Symbol	Parameter	WNM20N60SF	WNM20N60S	Unit
V_{DSS}	Drain-Source Voltage	600		V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$)	20 12	20* 12*	A A
I_{DM}	Drain Current - Pulsed	(Note 1)	60	60*
V_{GSS}	Gate-Source voltage		± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	600	mJ
I_{AR}	Avalanche Current	(Note 1)	20	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	20.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C	205 1.67	35 0.3	W W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C

Thermal Characteristics

Symbol	Parameter	WNM20N60SF	WNM20N60S	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.6	3.6	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	62	°C/W

Electrical Characteristics

$T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	600	--	--	V	
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^\circ C$	--	600	--	V	
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to $25^\circ C$	--	0.6	--	V/ $^\circ C$	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	--	--	1	μA	
		$V_{DS} = 480V, T_C = 125^\circ C$	--	--	10	μA	
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA	
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA	
On Characteristics							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	--	4.0	V	
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 10A$	--	0.155	0.19	Ω	
g_{FS}	Forward Transconductance	$V_{DS} = 40V, I_D = 10A$	(Note 4)	16	--	S	
Dynamic Characteristics							
C_{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$		--	1440	pF	
C_{oss}	Output Capacitance			--	345	pF	
C_{rss}	Reverse Transfer Capacitance			--	70	pF	
Switching Characteristics							
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400V, I_D = 10A, R_G = 20\Omega$	--	25	--	ns	
t_r	Turn-On Rise Time		--	55	--	ns	
$t_{d(off)}$	Turn-Off Delay Time		--	70	--	ns	
t_f	Turn-Off Fall Time		(Note 4, 5)	--	40	--	ns
Q_g	Total Gate Charge	$V_{DS} = 480V, I_D = 20A, V_{GS} = 10V$	--	70	90	nC	
Q_{gs}	Gate-Source Charge		--	9.5	--	nC	
Q_{gd}	Gate-Drain Charge		(Note 4, 5)	--	35	--	nC
Drain-Source Diode Characteristics and Maximum Ratings							
I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	20	A		
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	60	A		
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 20A$	--	--	1.5	V	
t_{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_S = 20A, dI_F/dt = 100A/\mu s$	--	475	--	ns	
Q_{rr}	Reverse Recovery Charge		(Note 4)	--	5.8	μC	

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 10A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ C$
3. $I_{SD} \leq 20A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
4. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

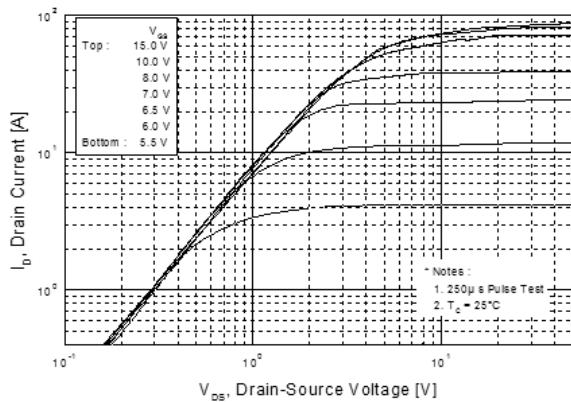


Figure 2. Transfer Characteristics

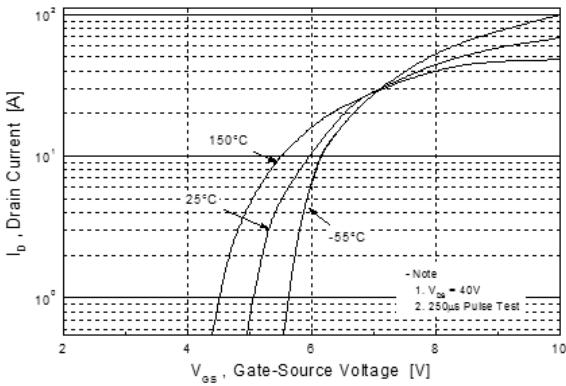


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

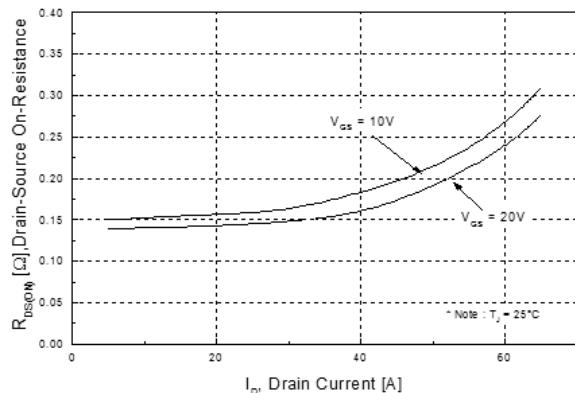


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

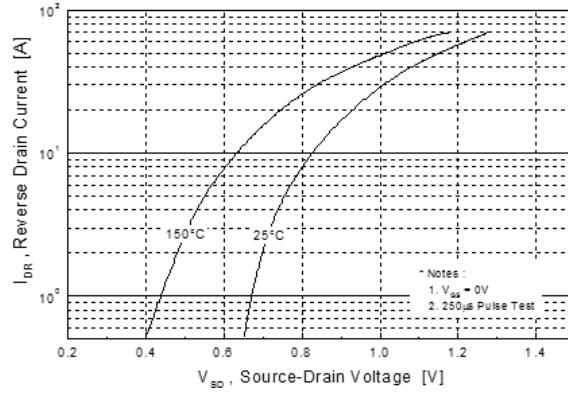


Figure 5. Capacitance Characteristics

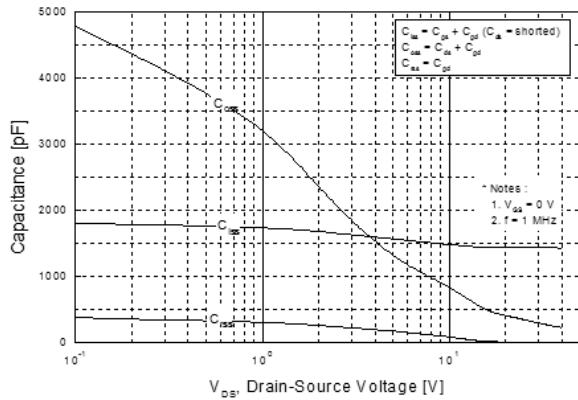
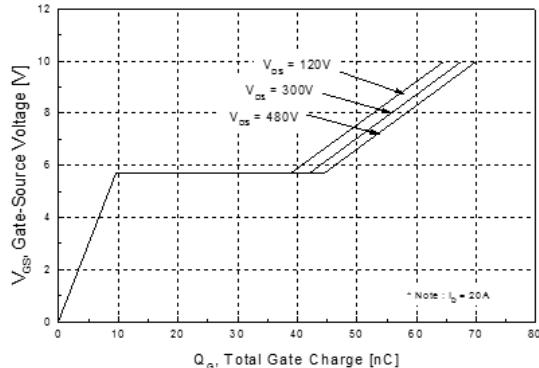


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

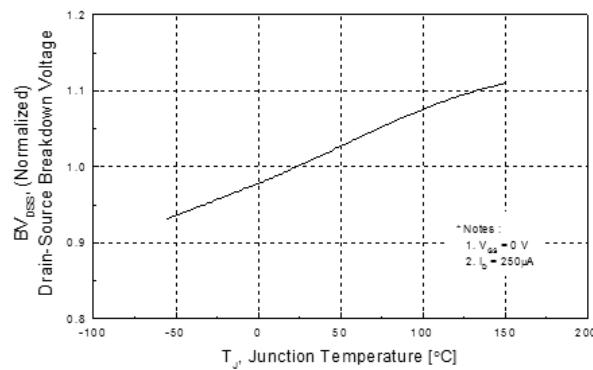


Figure 8. On-Resistance Variation vs. Temperature

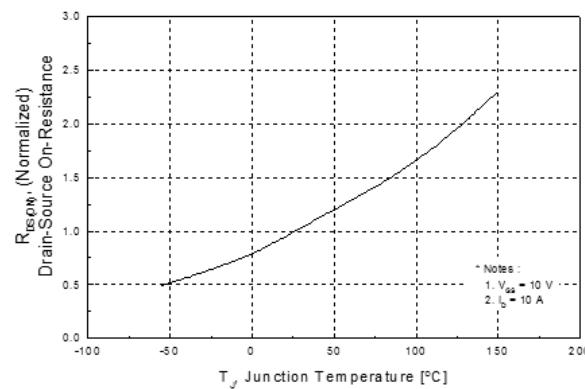


Figure 9-1. Safe Operating Area of WNM20N60SF

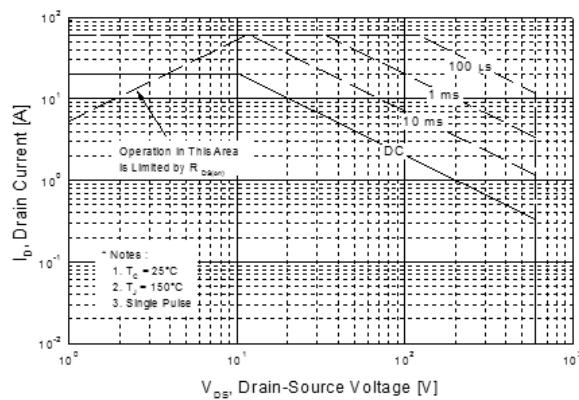


Figure 9-2. Safe Operating Area of WNM20N60S

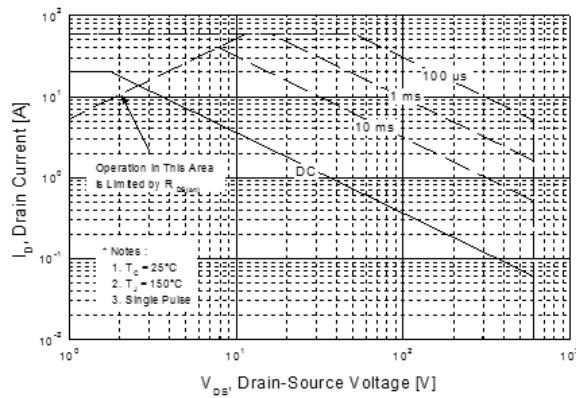
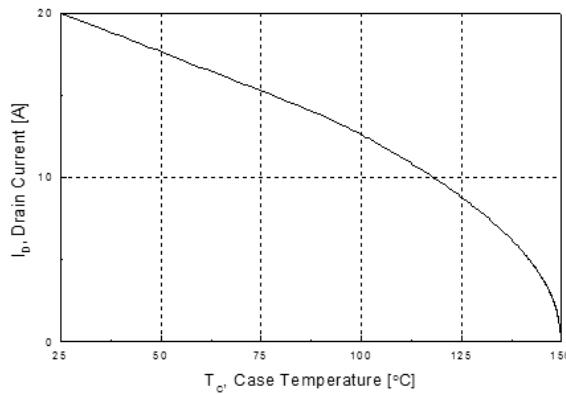


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 10-1. Transient Thermal Response Curve of WNM20N60SF

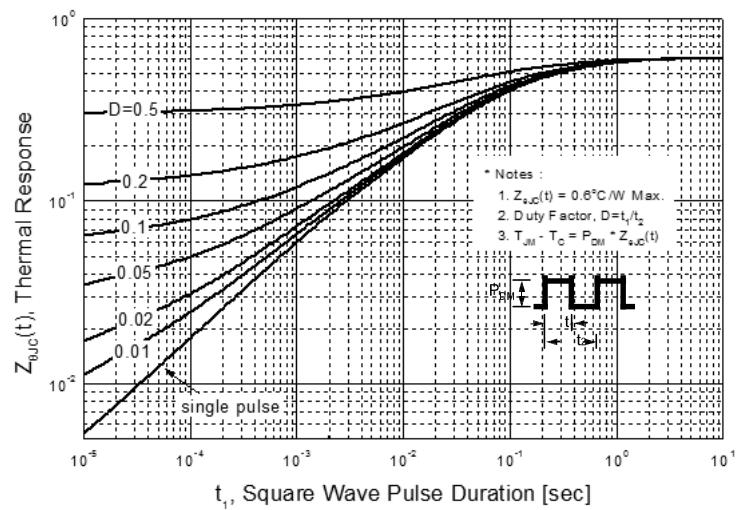
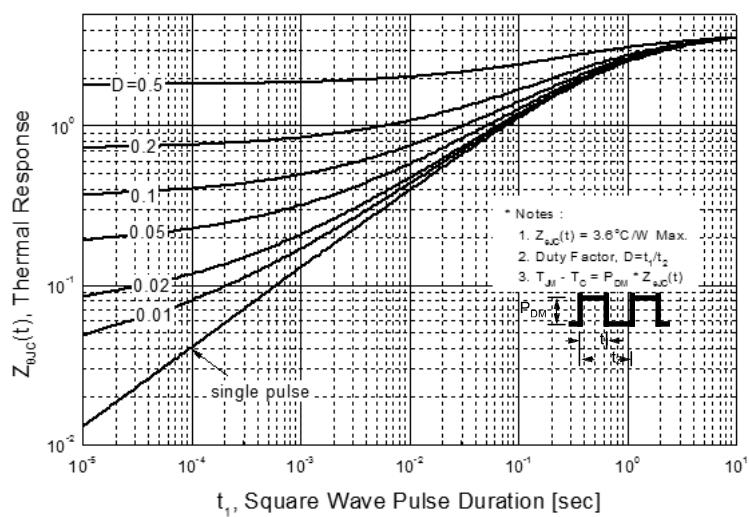
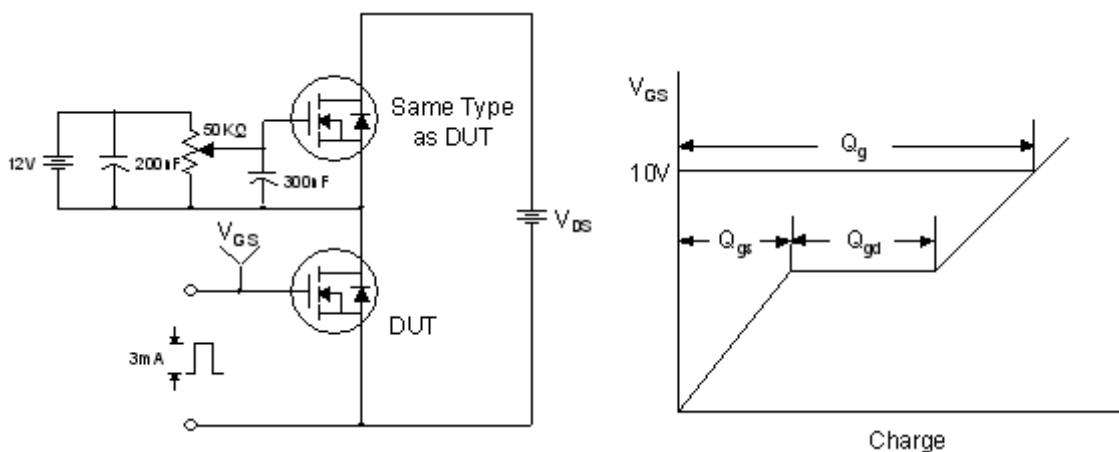
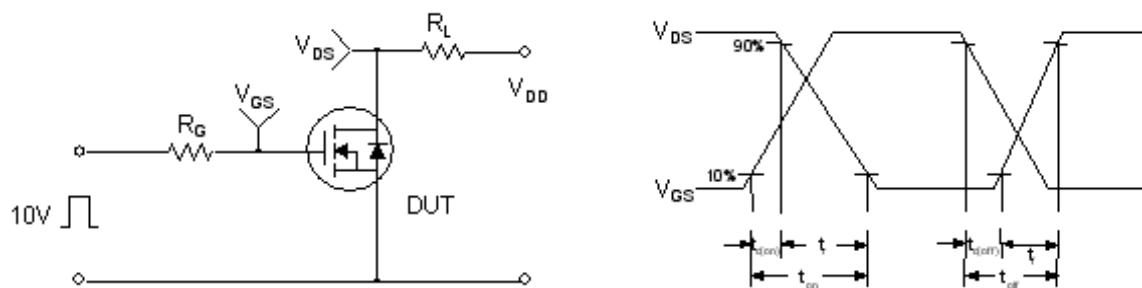
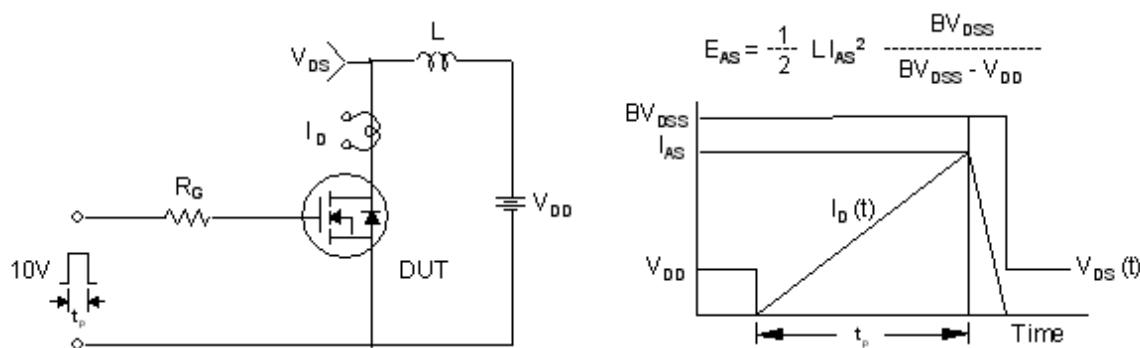
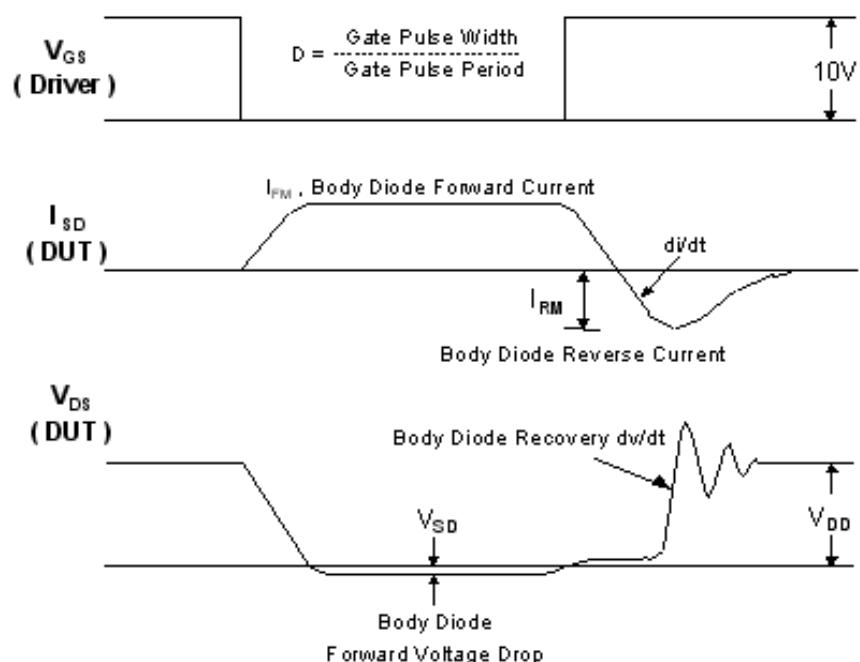
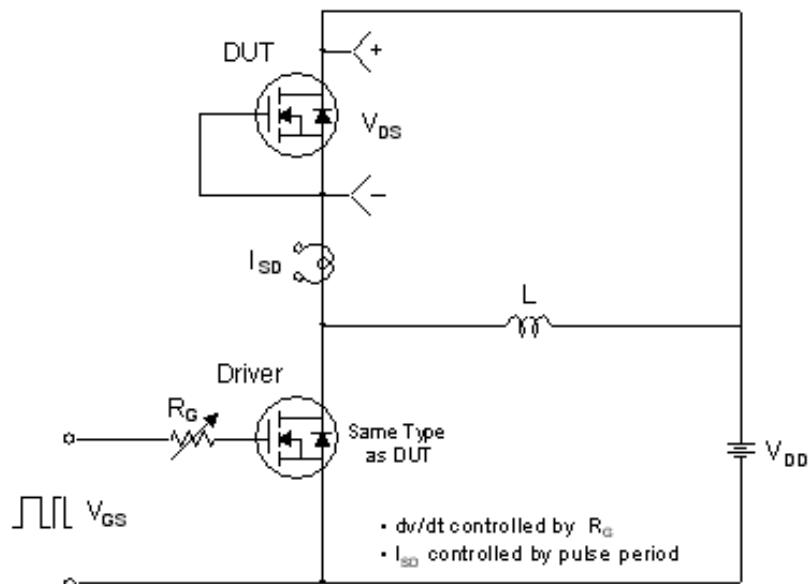


Figure 10-2. Transient Thermal Response Curve of WNM20N60S

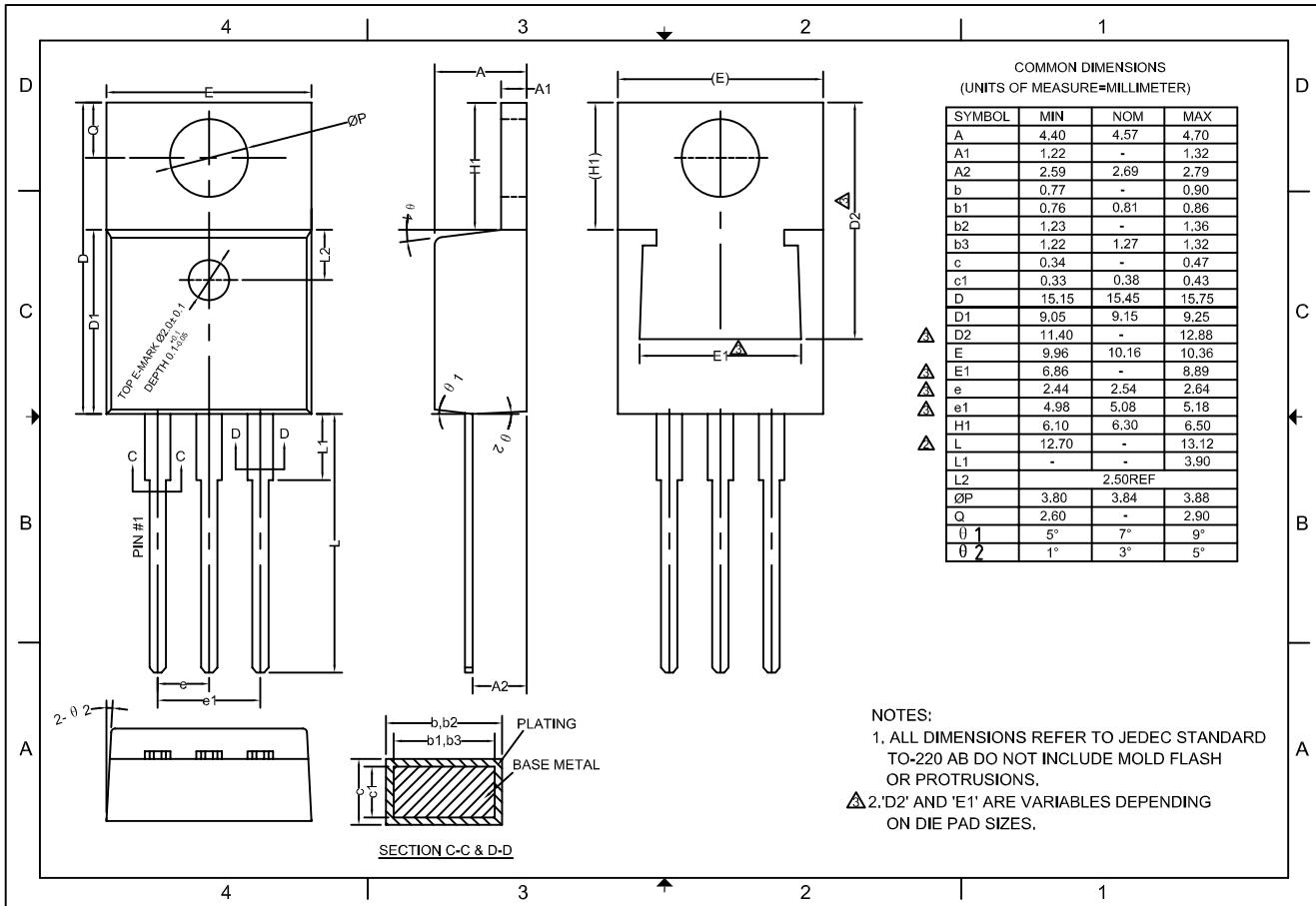


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Peak Diode Recovery dv/dt Test Circuit & Waveforms


Package outline dimensions

TO-220



TO-220F

